

26.0 GHz Surface Mount Bandpass Filter

B260MB2S

DESCRIPTION

One of DLI's surface mountable catalog bandpass filters designed for the 5G band. This filter utilizes DLI's low loss temperature stable materials which offer small size and minimal performance variation over temperature.

The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

FEATURES

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

Packaging and Ordering information:

To request tape and reel packaging, please order part number B260MB2S-T

SPECIFICATIONS*

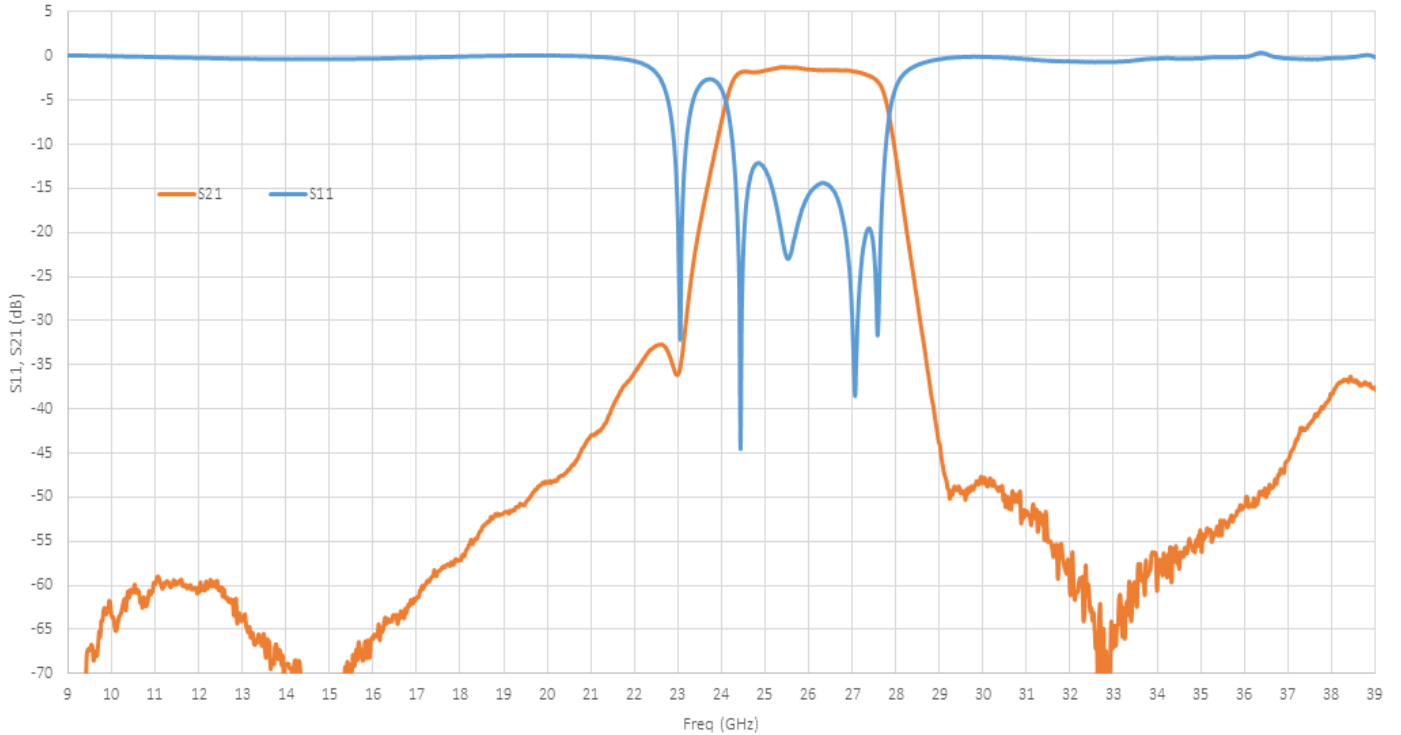
Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	24.25 - 27.5	—	1.3	2.3
Return Loss (dB)		12	15	—
Low Side Rejection (dB)	DC - 6.0	—	55	—
	6.0 - 16.0	—	50	—
	16.0 - 20.0	—	42	—
	20.0 - 23.0	—	30	—
High Side Rejection (dB)	28.5 - 29.5	—	21	—
	29.5 - 33.5	—	50	—
	33.5 - 36.0	—	50	—
	36.0 - 41.0	—	35	—
Size (L x W x H)	0.217x 0.090 x 0.064 in			
	5.5 x 2.3 x 1.8 mm			

*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ± 0.5 dB over temperature.

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RF Measured Performance

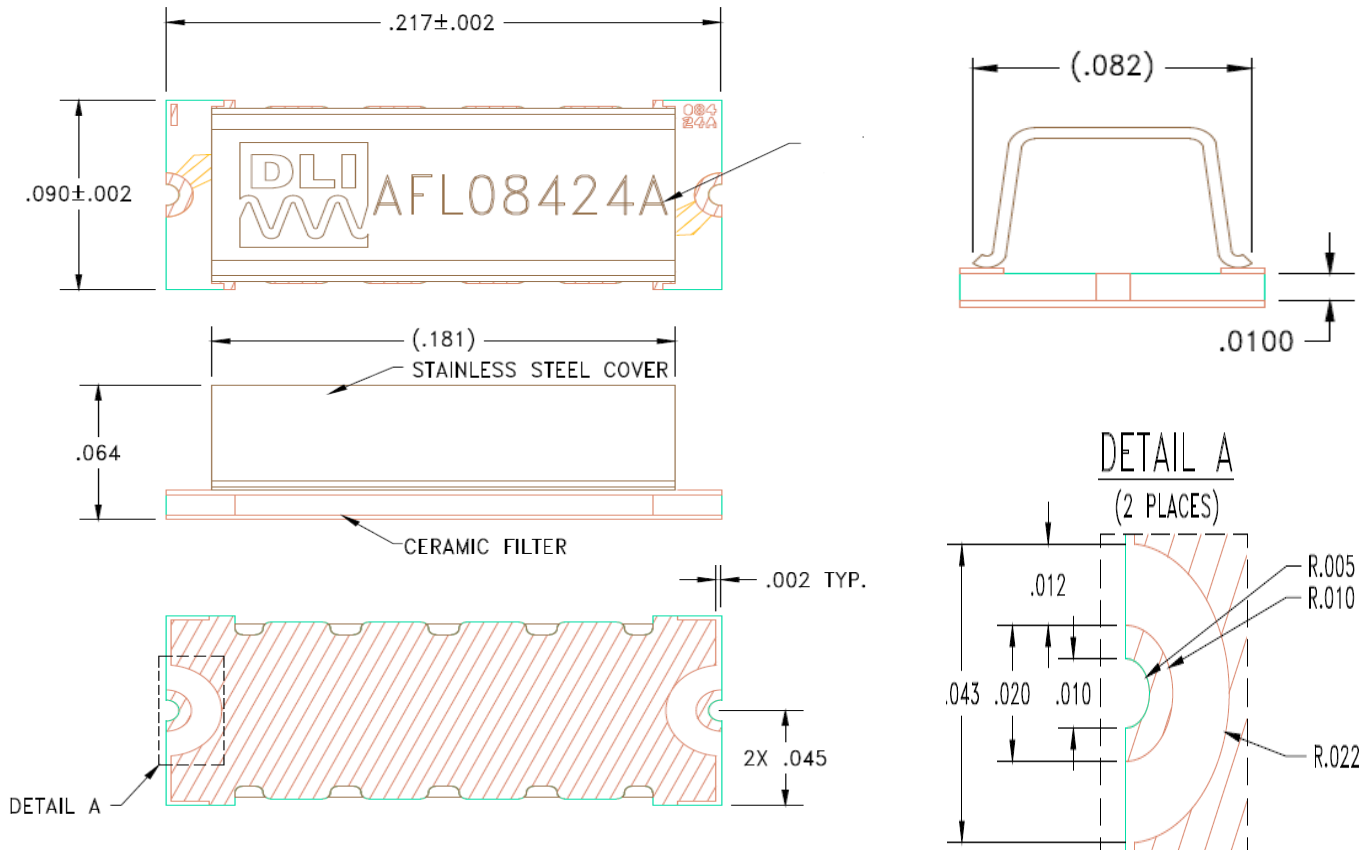


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Physical Dimensions

Units = inches (in)



NOTES:

1. MOUNTING SURFACE METALLIZATION:
3–6 μINCHES Au OVER
50 μINCHES MIN. Ni OVER
100 μINCHES MIN. Au OVER
300 Å MIN. TiW
2. COVER MATERIAL:
ANNEALED, 430 STAINLESS STEEL
3. COVER METALLIZATION:
5–15 μINCHES Au OVER
50–100 μINCHES Ni
4. ASSEMBLY WILL BE LASER MARKED AS SHOWN.
5. MAXIMUM ASSEMBLY PROCESS TEMPERATURE: 250°C

- 50Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.

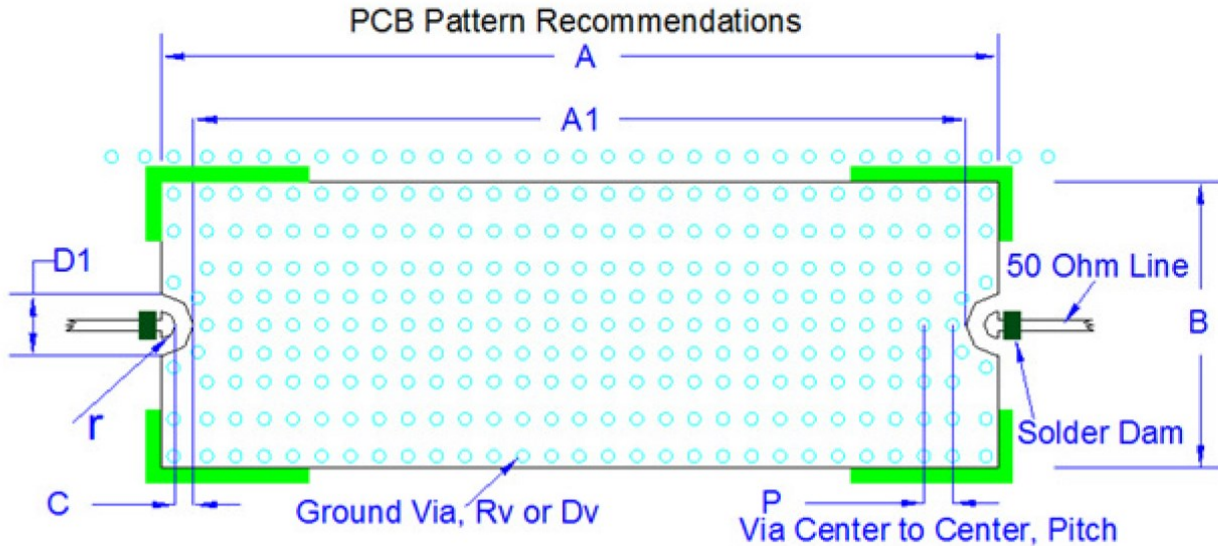


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PCB Pattern Recommendations

Unit : mm



Unit: mm

L	W	D1	D2	R	R	A	A1	B	C
5.5	2.3	1.1	0.5	0.5*D2	R	L	L-D1	W (Min)	0.55

Rv	Dv	P
0.15	2*Rv	0.5

- Longer via hole center-to-center distance or pitch P may degrade filter Rejection and other performance.
- PCB thickness is 0.254mm. For thicker PCB, P should be reduced accordingly.
- For high-frequency and high-performance filters, EM simulations for PCB layout are highly recommended.